



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Min-Lung HUANG et al. Confirmation No: 8687
Appl. No. : 10/820,855
Filed : April 9, 2004
Title : Under Bump Metallization Structure Of A Semiconductor Wafer

TC/A.U. : 2814
Examiner : A. Kalam

Docket No.: : HUAN3262/REF
Customer No: : 23364

PETITION FOR EXTENSION OF TIME

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Applicants request that the period for response to the outstanding official action in this case be extended pursuant to 37 CFR 1.136 (a) for THREE (3) months to February 27, 2008.

The fee set in 37 CFR 1.17(a)(2) for a three month extension of time is \$1,050.00, however a check in the amount of \$120.00 for a one (1) month extension of time was submitted on December 27, 2007. Therefore, a check in the amount of \$930.00 of the balance due is submitted herewith. Please charge any additional fee required for this extension to Deposit Account No. 02-0200. A duplicate copy of this paper is attached.

Respectfully submitted,
BACON & THOMAS, PLLC

By: Richard E. Fichter
Richard E. Fichter
Registration No. 26,382

625 Slaters Lane, 4th Fl.
Alexandria, Virginia 22314
Phone: (703) 683-0500
Facsimile: (703) 683-1080
REF:cjw
EXT 2 MO - LG.wpd
February 26, 2008

02/27/2008 MBELETE1 00000023 10020855

02 FC:1253

930.00 0P